

Mechanical Structure for EPIC TOF

6th June 2023

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○ Budget

- 2022 – 2023: 30K (include material and cost of processing)
 - 2023 – 2024: 30K (include material and cost of processing)
 - 2024 – 2025: 30K (include material and cost of processing)
- Purdue Deliverable: One 1.35m “plank” prototype until Sept 2023
 - Budget: 10% FTE engineer ~15k\$ + low S&E \$\$
 - Materials: cost-effective by using non-final materials and usage of FEA
 - Lots of relevant experience to draw from and apply to benefit of EIC

○ Goals:

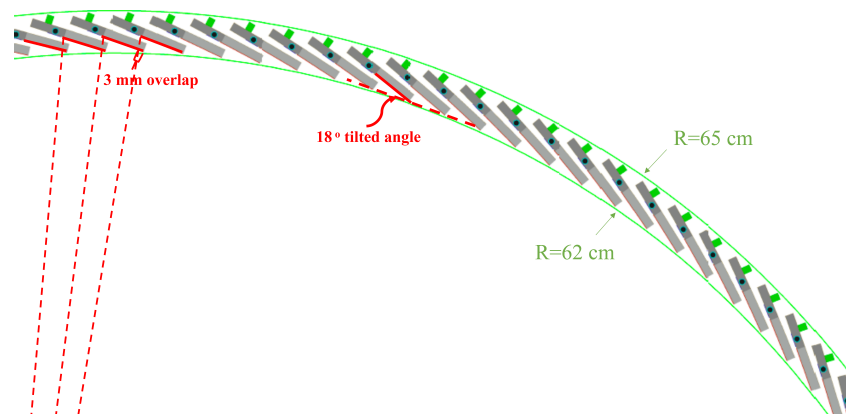
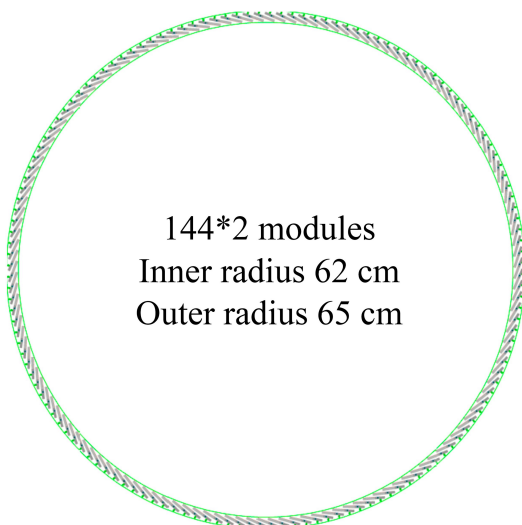
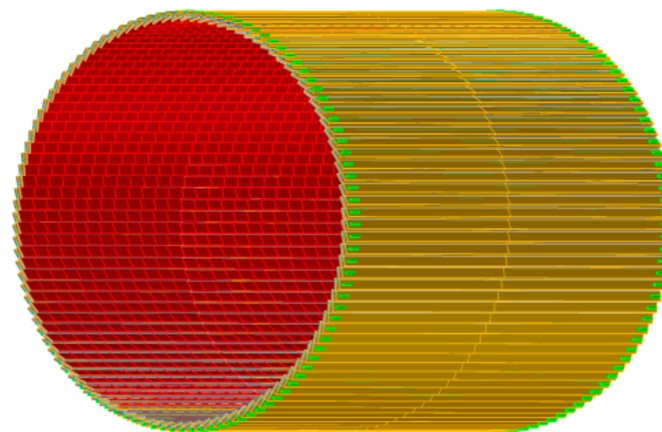
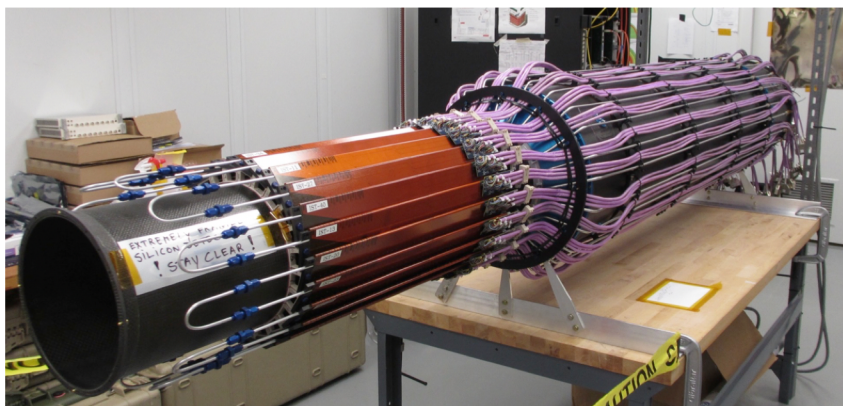
- Integrated cooling and mechanical support structures
- Average material budget 1% X_0 or smaller
- Cooling capable of dealing with multi-kW power dissipation

○ Deliverables: 1-3 “stave” structures, i.e. no larger system aspects.

○ Latest Updates:

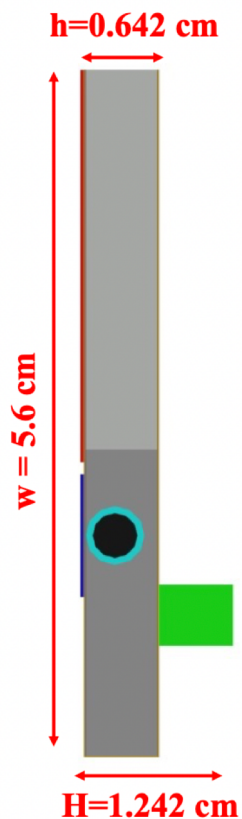
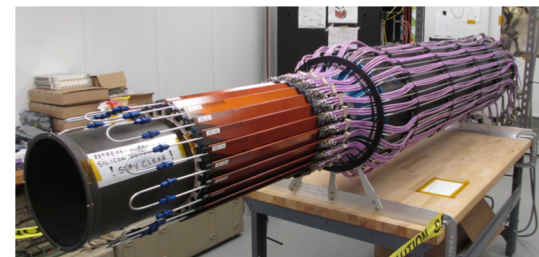
- Paperwork / SOW submitted
 - Purdue to BNL (late, on 31st March)
 - NCKU to JLAB (TBC)

- Use the similar concept of STAR IST

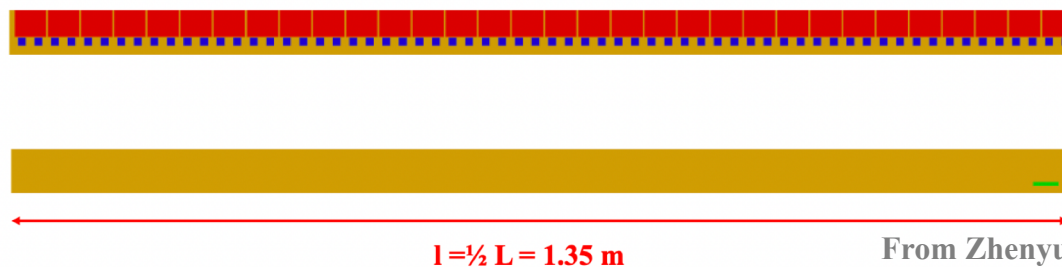
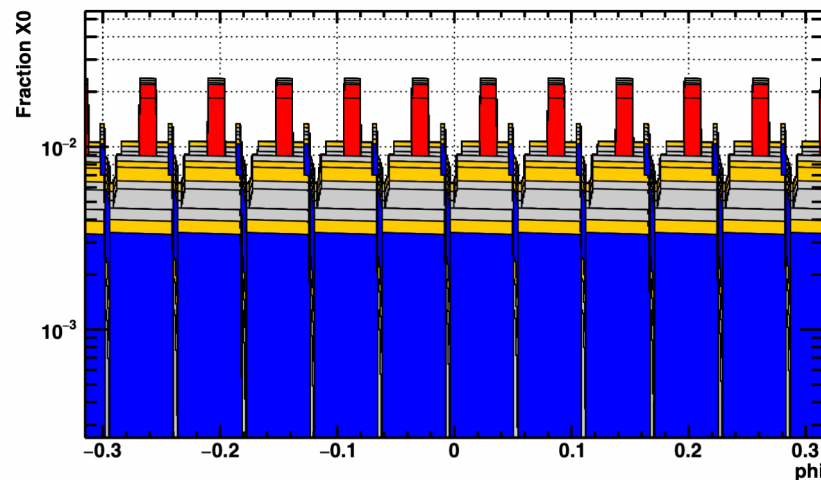


From Zhenyu's talk
<https://indico.bnl.gov/event/16765/>

- In total 288 modules,
 - 9216 sensors, 18,432 ASICs, 2.4 M channels
 - ~70 kG, ~4 kW

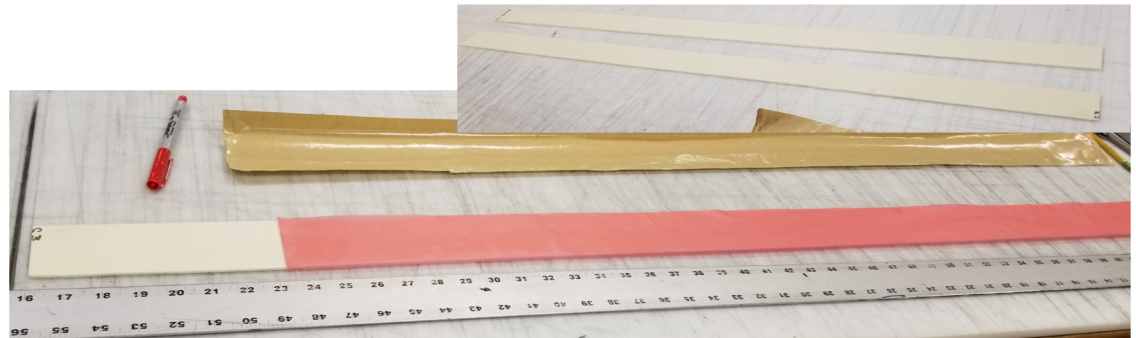


- **AC-LGAD sensor**
- **Frontend ASICs**
- **Carbon foam+ Carbon honeycomb+ CF skins**
- **Al cooling tube**
- **Liquid coolant**
- **Kapton PCB**
- **Connector**

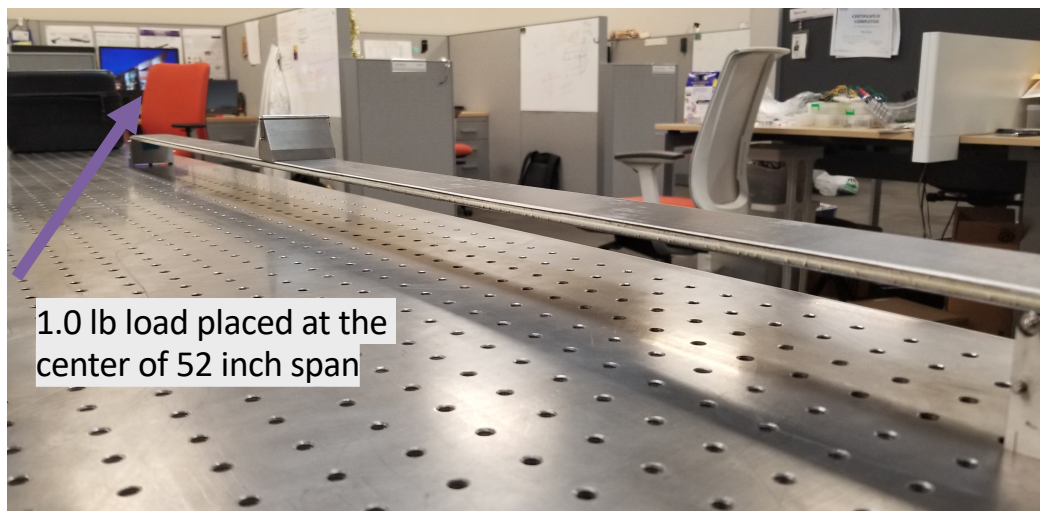


From Zhenyu's talk
<https://indico.bnl.gov/event/16765/>

- **First limited activities started...**
- CAD model based on the STAR IST staves
- Dimensions as follows – total thickness is 6.9 mm (0.2 mm facesheet [0/90/0] + 3.25 mm foam + 3.25 mm foam + 0.2 mm facesheet [0/90/0])
- Foam material used – Airex 82.80
- Face sheet – Rockwest EHM32 / T700 – 250 F cure – UD prepreg – layup [0/90/0]

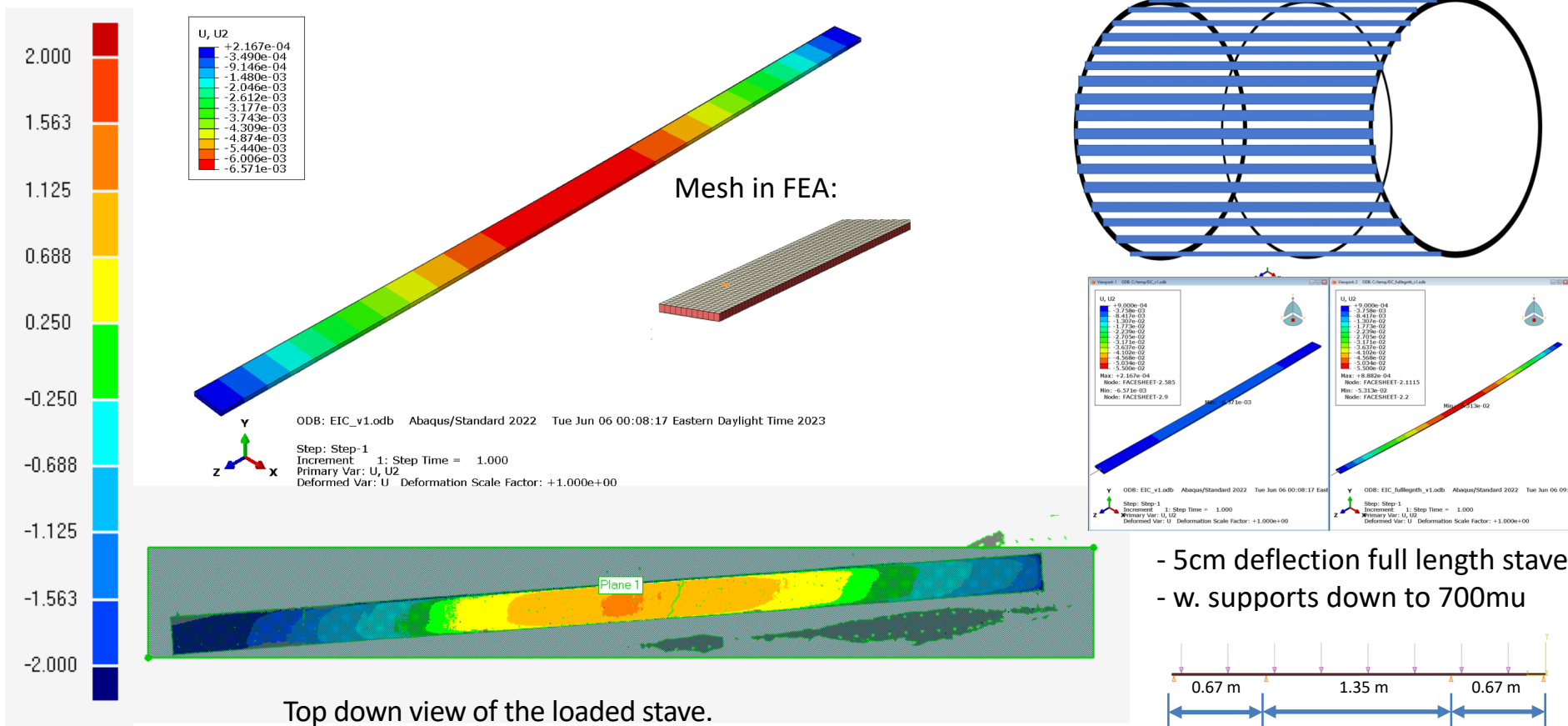


○ Loading test w 1lb load in the center....



○ FEA results...preliminary

- FARO is at 6mm deflection, FEA at 2mm (longer worse, ~5cm)
 - Caveat: no pipe in it...not enough time.
- Calls for support structure which is to come – see here:



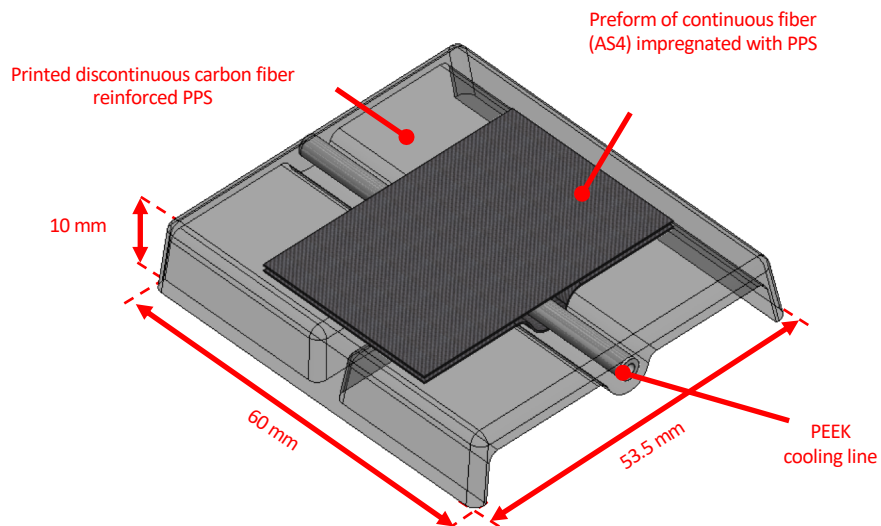
- 5cm deflection full length stave
 - w. supports down to 700mm

- PED request and TOF-LGAD mechanics team evolved since FY23 R&D
- Goals:
 - Includes a support structure for the barrel TOF-LGAD, see earlier slides
 - Look at a 1st concept for cooling performance (but relies on holistic detector wide concept)
 - Lots of synergies between R&D and PED...
 - MPGDs support relevant for barrel TOF-LGAD support, meet 8th June 2pm – thanks for setting this up. Needs to be discussed...

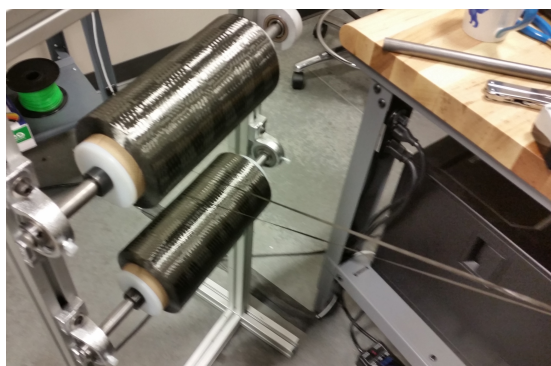
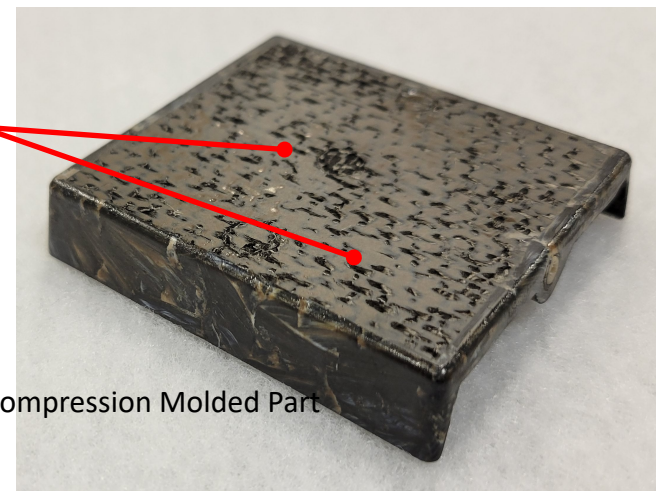
Resource	FTE (%)	Budget (k\$)
Manufacturing Design of pre-production		
Mechanical Engineer + Technician, Purdue	50	150
UG students, Purdue	20	0 (in-kind)
Postdoc, NCKU	20	0 (in-kind)
G/UG students, NCKU	20	0 (in-kind)
Materials and Supplies (stave supports, endcap discs, etc.)	-	35
Integration aspects / Services		
Mechanical Engineer, Purdue	20	40
Total	-	225

Table 1: Purdue/NCKU budget request on engineering design for barrel TOF in FY23. All entries in thousands of dollars.

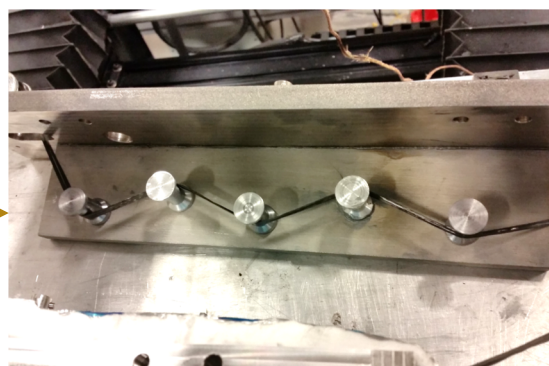
○ Could be applicable to EIC – recent progress...



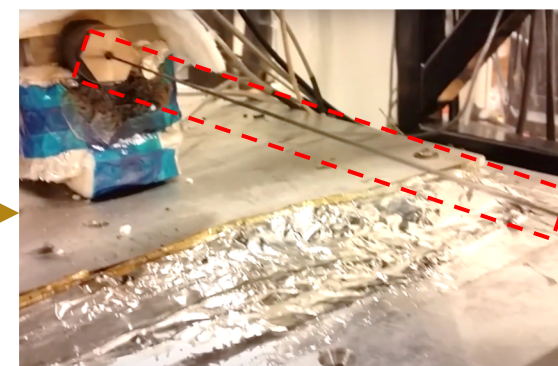
Continuous CF exposed at the surface for enhanced thermal conduction.



Spools of Carbon Fiber



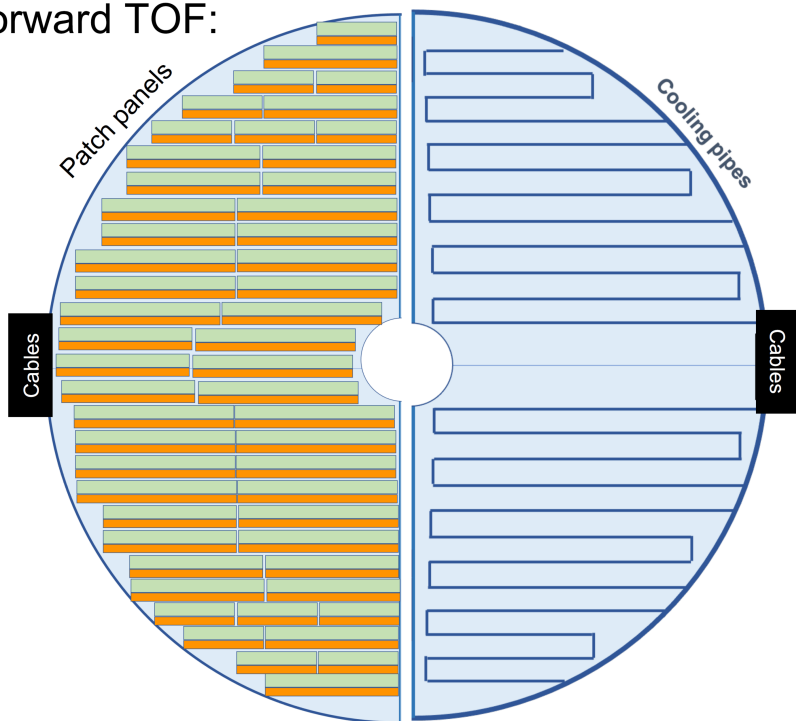
Interior of Impregnation Chamber



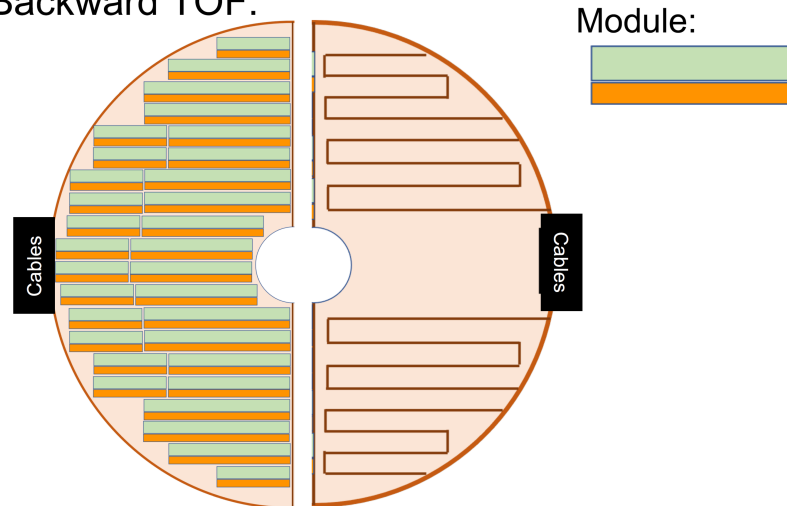
Carbon Fiber Impregnated with PPS

From the talk of Wei Li
<https://indico.bnl.gov/event/16742/>

Forward TOF:



Backward TOF:



- “Clam shells” or DEEs
 - Convenient for installation/maintenance
 - Each is patched by TOF modules (one or more types) on both faces

Power Budget

	Forward	Backward
Sensors	0.6kW	0.35kW
EPTROC	8.5kW (17kW)	4.8kW (9.6kW)
DC-DC	3.5kW	2kW
IpGBT, VTRx+, SCA	0.5kW	0.3kW
Power cables	0.5kW	0.3kW
Total	13.6kW (22.1kW)	7.75 (12.55kW)

○ **Theme: RD request to push for endcap solution, whole system support + staves folded into PED request**

○ **Budget**

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- Purdue Deliverable: 1-3 “wedge” prototype until Sept 2024
 - Budget: 10% FTE engineer ~15k\$ + low S&E \$\$
 - Materials: cost-effective by using non-final materials and usage of FEA
 - Lots of relevant experience to draw from and apply to benefit of EIC

○ **Goals:**

- Develop and push a light-weight solution for endcap compatible with needs of subsequent detectors

○ **Deliverables: 1-3 “wedge” structures, incl. solution for connections**

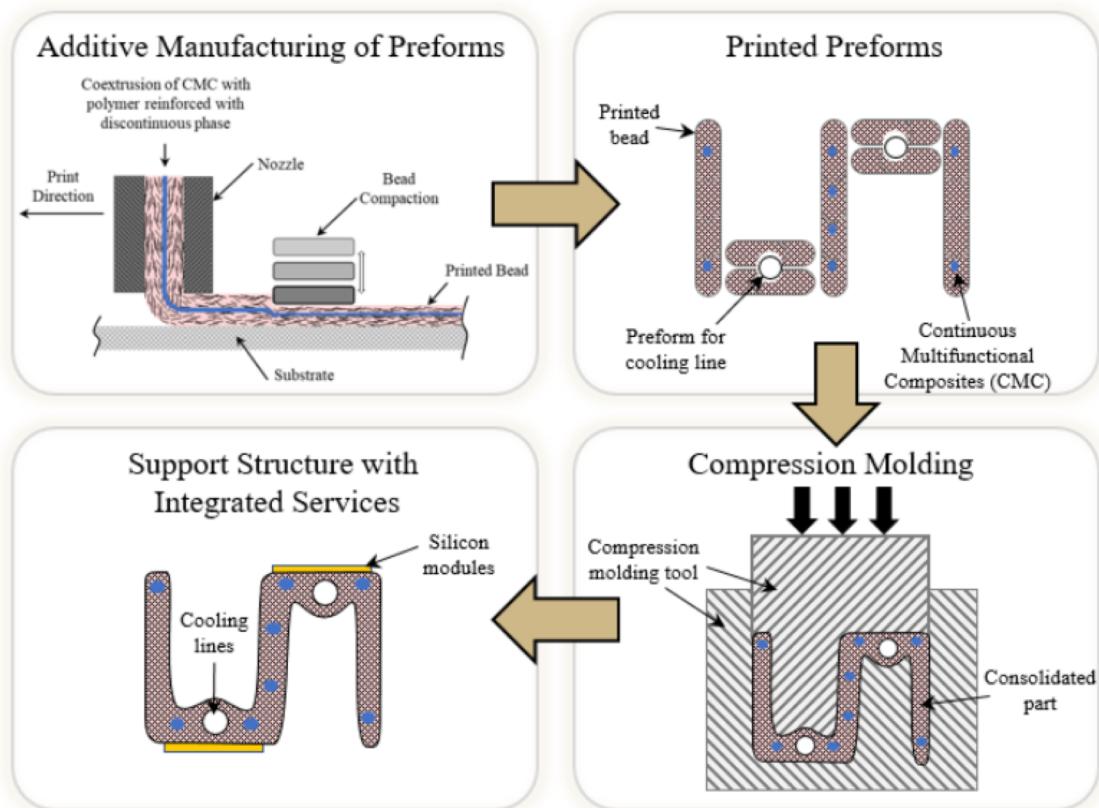


Backups

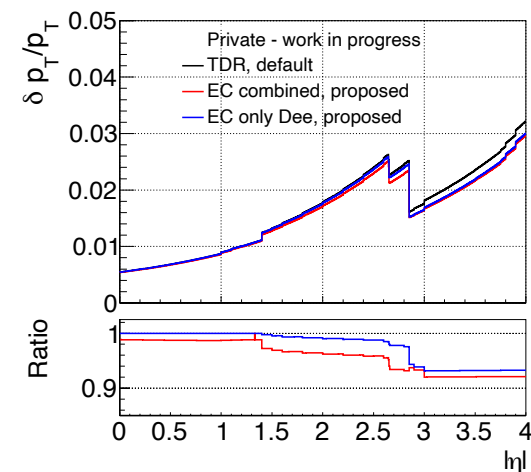


○ Identified by DOE BRN effort

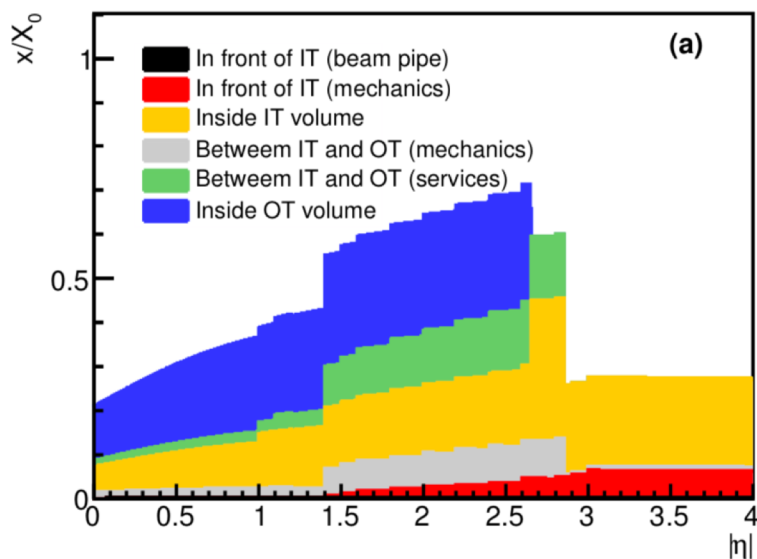
- Scaling of low-mass detector system towards irreducible support structures with integrated services. Includes: integrated services, power management, cooling, data flow, and multiplexing.
- Purdue proposed to DOE:



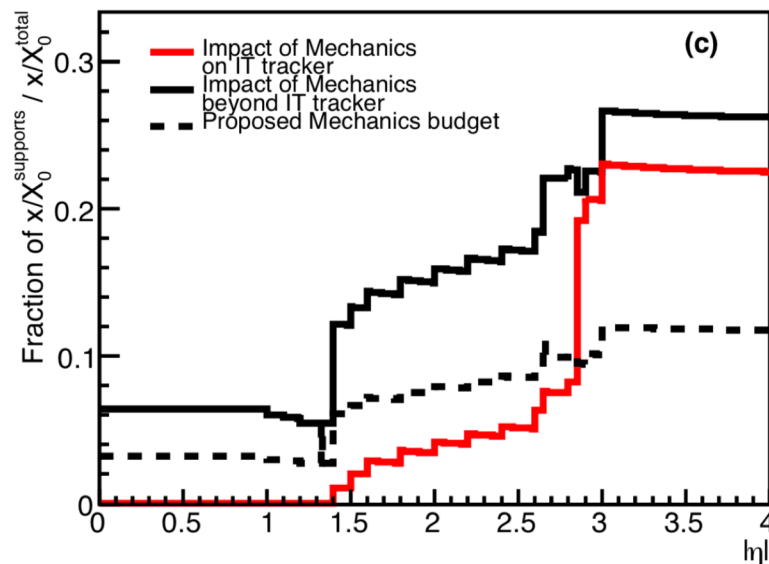
- Radiation length plot more specific to EIC (hope to get that one done till 6th)
- These techniques more easy benefit endcap detectors whereas gains are limited in barrel region
- This seems like a good fit to the needs of TOF



Example from CMS....



Aggressive design...

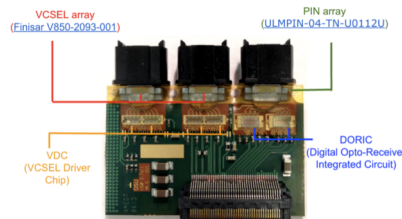




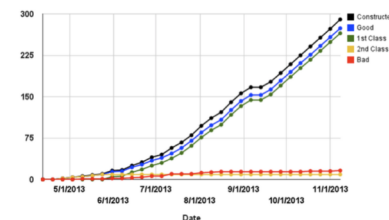
○ Purdue University

- Andreas Jung, previous experience
 - CMS IT mechanics convener (2017-2020)
 - Leading the Barrel, Forward and Extended Pixel projects
 - Mechanics leadership in CMS
 - Technical lead for the CMS BTST project, Contact for procuring all high thermal conductive CF needs in CMS and leading the related R&D at Purdue
 - Coordinating tracker mechanics projects (ITST, SC, OT, BTST) at Purdue.
 - Associated member of the Composite Manufacturing & Simulation Center at Purdue University
 - DOE Blue Sky R&D grant for irreducible tracker support structures for detectors at future colliders (FCC, ILC, muon, etc.)
 - Operation & Optimization of track trigger at H1 (HERA), and operation of silicon tracker at D0 (Tevatron)

- **2012 – 2014 (@OSU):** Project manager for the Opto-board for inner detector

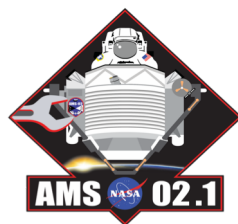


Photograph of an opto-board

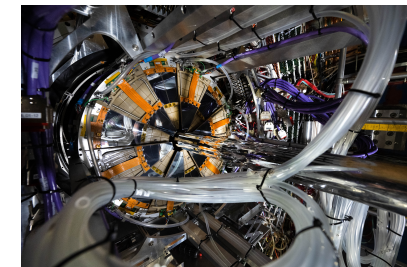
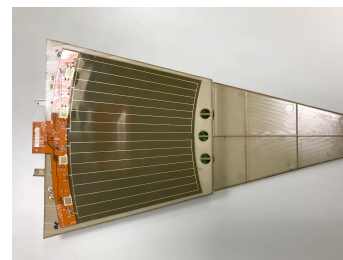


Opto-board production status

- **2015 – 2018 (@NCKU):** Project leader for the AMS-02 UTTPS radiator

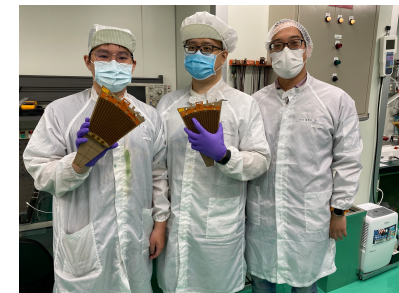
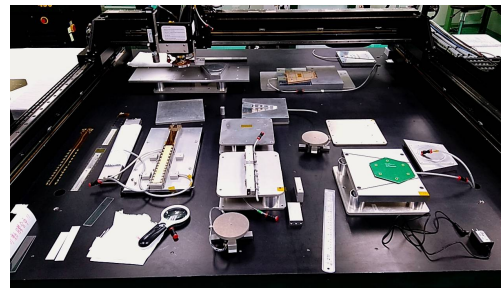


- **2018 – 2021 (@NCKU):** Deputy manager for the STAR FST, project leader for the mechanical structure for FST



○ Taiwan Instrumentation and Detector Consortium (TIDC):

- <https://tidc.phys.ntu.edu.tw/WordPress/>
- Sophisticated machines for detector assembly



○ NCKU:

- Strong mechanical engineering department
- Good relationship with Aerospace Industrial Development Corporation (expert on composite material)

○ AS IoP:

- High precision machine shop



○ Three mechanical engineers from AS, NCKU and TIDC

STAR Forward Silicon Tracker

Flexible hybrid PCB: **SDU/IU**

Inner Signal Cable: **BNL/IU**

T-Board: **SDU/IU**

APV25 Chip: **UIC**

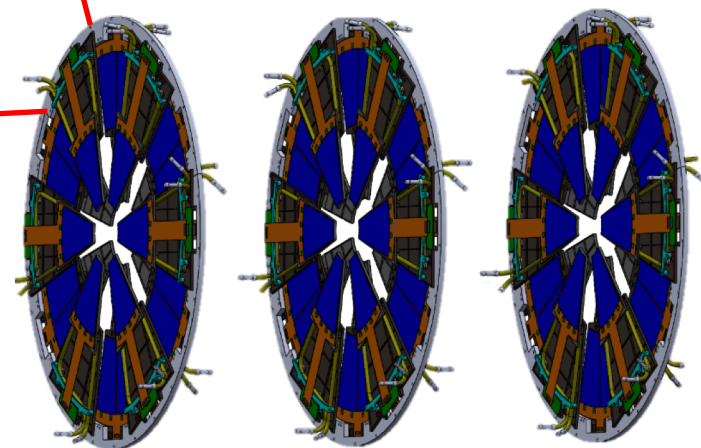
Mechanical Structure
(+ cooling pipe): **NCKU/AIDC**

Supporting Structure &
Integration: **BNL**

Silicon sensor: **UIC/BNL**

Cooling: **BNL/NCKU**

Simulation: **UIC/BNL/IISER/NCKU**



○ Composite Manufacturing & Simulation Center (CMSC) at Purdue, completed in summer 2016

- Purdue Center of Excellence across disciplines: Aeronautics, Chemical Eng, Materials Eng, Aviation Tech, Computer graphics, **and Physics**
- A. Jung – Associated member of CMSC

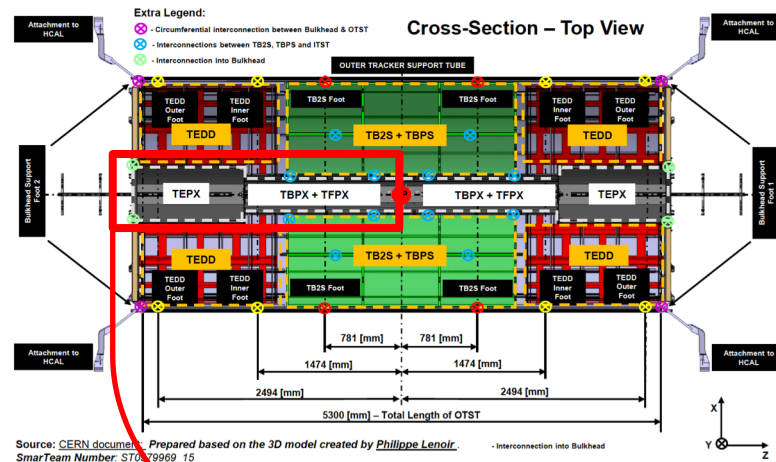
○ Professional composite experience:

- Seven full-time technical staff, five post-doctoral researchers, twenty grad's
- 35,000 sq. ft. of office and laboratory space
 - 2 large pressurized ovens, 1 larger oven with vacuum hook-ups
 - Larger ovens accessible with industry partners

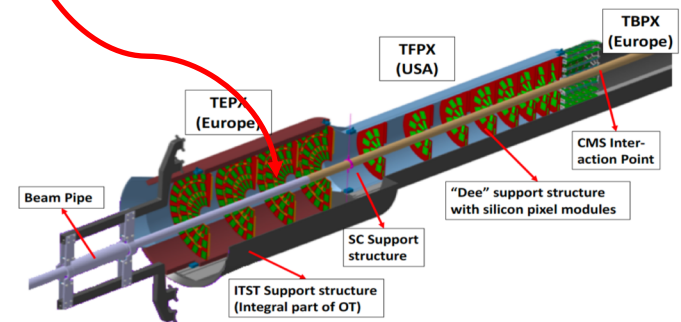


○ CMS upgrade relies on Purdue for design & manufacturing of mechanical support structures

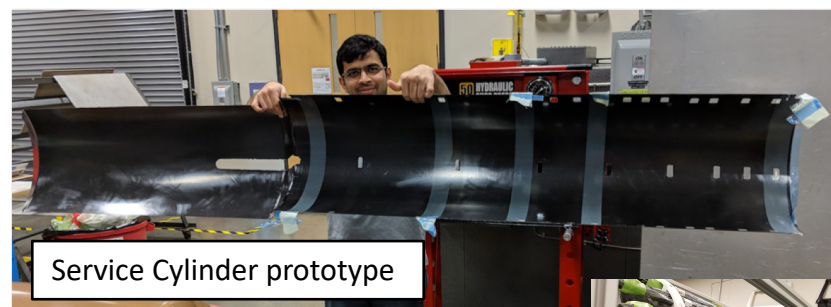
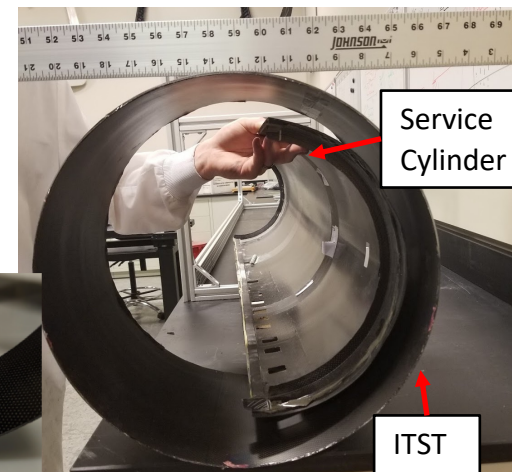
- Service Cylinder housing the Inner Tracker (IT)
 - 4+2 half cylinder structures with a length of 2.9m and transition region between small & large radii
 - Barrel, Forward, and Extended Pixel Detectors
- Components for Inner Tracker pixel
 - Sandwich structures to mount pixel modules (Dee's) for the forward pixel (US project)
 - CFRP structures for the barrel pixel (European led)
- Inner Tracker Support Tube (ITST)
 - Supports the 4 IT Service Cylinders, separates Inner Tracker and Outer Tracker volumes
 - Longitudinal stiffness for the entire Outer Tracker
- Components for Outer Tracker (OT) modules
 - CFRP stiffeners for the OT modules assembly
- Barrel Timing Layer Tracker Support Tube
 - Support the entire IT + OT + Timing Layer of CMS


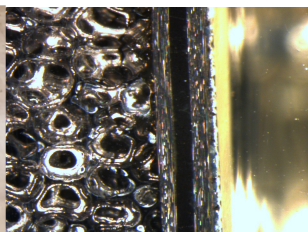
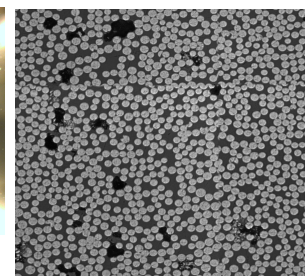


Source: CERN document. Prepared based on the 3D model created by Philippe Lenoir. SmarTeam Number: ST079969_15




- Prototyping & Manufacturing related to ITST, SC, Dee's
 - Prototypes confronted with FEA predictions, multiple iterations
 - Prototyping and Development of additional structures for IT pixel
 - Cartridges, Portcard holders, all extensively studied for high thermal performance
 - Accompanied by irradiation campaigns: sample prep, characterization, etc.
 - Dedicated measurement of thermal conductivities
 - High thermally conductive materials for 3D printed parts

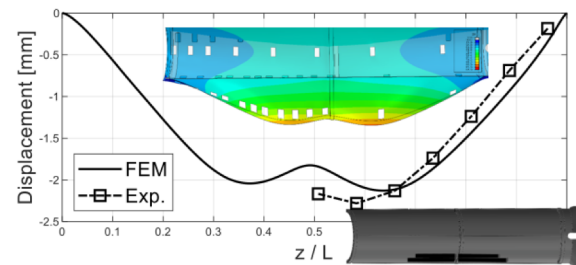


- Forward pixel dee prototype
- Co-cured samples
- Microscopies
- 3D printed mechanical supports
- Critical interfaces via FEA

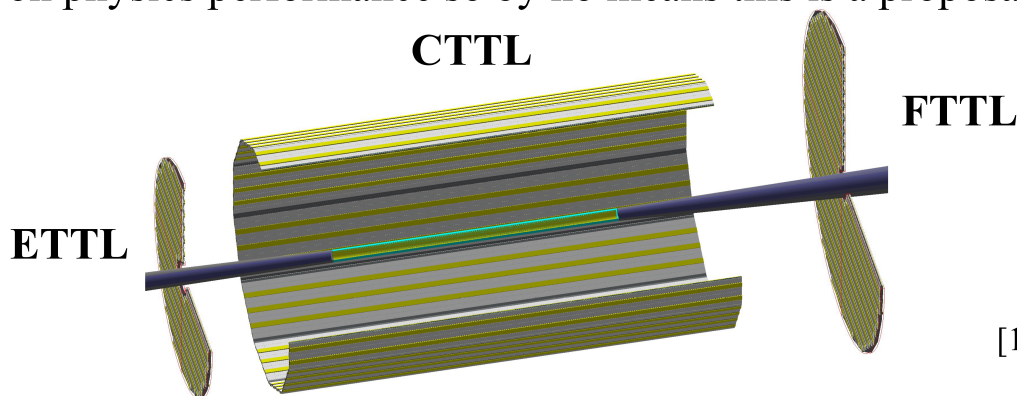


Through-plane thermal conductivity [W/mK]	Carbon fiber [K]	Carbon foam [K]	Epoxy [K]	TIM [K]
0.1	24	24	24	24
1	10	18	12	10
10	9	14	10	9
100	9	11	10	9



AC-LGAD Layer for TOF PID + Tracking

- The goal is to conceive a reference layout and technical design (v0) as inputs to GD/I group to advance the detector integration (service routing etc.)
- However, there are still on-going studies to investigate the optimal channel granularity based on physics performance so by no means this is a proposal for final design.



For v0 design, we propose:

- **Barrel: 0.5x10 mm² strips**
- **Endcap: 0.5x0.5 mm² pixels (same as RPs) [1]**

[1] Wei Li, TOF-PID WG Meeting Aug 29, 2022

	acceptance	Z (m)	Radius (m)	Area (m ²)	Channel size (mm ²)	# of Channels
ETTL	$-3.7 < \eta < -1.74$	-1.61 to -1.71	0.12 to 0.63	1.20	0.5*0.5	4.8M
CTTL	$ \eta < 1.4$	-1.2 to 1.5	0.625 to 0.655	10.9	0.5*10	2.4M
FTTL	$1.5 < \eta < 3.5$	1.555 to 1.705	0.12 to 0.85	2.22	0.5*0.5	8.8M